

#31neandt #
A. Chestnut
12-3-99

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Rich Fogal and Michael B. Ball

Serial No.:

Filed: October 21, 1999

For: ANGULARLY OFFSET STACKED DIE
MULTICHIP DEVICE AND METHOD OF
MANUFACTURE

§
§ Group Art Unit:
§
§ Examiner:
§
§ Atty. Docket: 95-0134.05
§
§
§
§

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

"EXPRESS MAIL" MAILING LABEL NO. EL003001708US
DATE OF DEPOSIT <u>10-21-99</u>
I HEREBY CERTIFY THAT THIS PAPER IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE "EXPRESS MAIL POST OFFICE TO ADDRESSEE" SERVICE UNDER 37 C.F.R. § 1.10 ON THE DATE INDICATED ABOVE AND IS ADDRESSED TO THE ASSISTANT COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.
<i>Rich Fogal</i> Signature

Dear Sir:

After awarding the above-captioned application the benefit of the priority date of its great-grandparent application, serial no. 08/515,719, filed August 16, 1995, please amend the current application as follows.

IN THE SPECIFICATION:

Immediately before the section labeled DESCRIPTION, please add the following: --

Related Applications

This application is a divisional of application serial number 09/122,666, filed July 24, 1998; which is a continuation of application serial number 08/741,579, filed November 1, 1996 and

A1
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